

Application Number: 10/654,167
Reply to O.A. of April 13, 2005

Dkt. No.: DT-024-US-01

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A hot melt adhesive composition comprising:
 - (a) an ethylene methyl methacrylate copolymer;
 - (b) a wax; and
 - ~~(b)~~(c) a tackifying resin,with the proviso that the composition does not include a surfactant or a copolymer of ethylene and n-butyl acrylate.
4. (Currently Amended) The composition of claim ~~3~~ 2 further comprising an antioxidant.
8. (Currently Amended) The composition of claim ~~7~~ 1 further comprising a block copolymer.
11. (Currently Amended) A hot melt adhesive composition consisting essentially of:
 - (a) an ethylene methyl methacrylate copolymer;
 - (b) a wax; and
 - ~~(b)~~(c) a tackifying resin.
14. (Currently Amended) The composition of claim ~~13~~ 12 further consisting essentially of an antioxidant.
17. (Currently Amended) The composition of claim ~~16~~ 11 further consisting essentially of a block copolymer.

Please cancel claims 3, 7, 13, and 16.

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DETAILED CLAIM LISTING

The listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Currently Amended) A hot melt adhesive composition comprising:
 - (a) an ethylene methyl methacrylate copolymer;
 - (b) a wax; and
 - ~~(b)~~(c) a tackifying resin,with the proviso that the composition does not include a surfactant or a copolymer of ethylene and n-butyl acrylate.
2. (Original) The composition of claim 1 further comprising an oil.
3. (Cancelled)
4. (Currently Amended) The composition of claim 3 2 further comprising an antioxidant.
5. (Original) The composition of claim 4 further comprising a copolymer.
6. (Original) The composition of claim 5 further comprising a block copolymer.
7. (Cancelled)
8. (Currently Amended) The composition of claim 7 1 further comprising a block copolymer.
9. (Original) A package formulation comprising:
 - (a) the composition of claim 1; and
 - (b) instructions for application of the composition to a substrate.

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10. (Withdrawn) A method of making the composition of claim 1.
11. (Currently Amended) A hot melt adhesive composition consisting essentially of:
 - (a) an ethylene methyl methacrylate copolymer;
 - (b) a wax; and
 - ~~(b)~~(c) a tackifying resin.
12. (Original) The composition of claim 11 further consisting essentially of an oil.
13. (Cancelled)
14. (Currently Amended) The composition of claim ~~13~~ 12 further consisting essentially of an antioxidant.
15. (Original) The composition of claim 14 further consisting essentially of a block copolymer.
16. (Cancelled)
17. (Currently Amended) The composition of claim ~~16~~ 11 further consisting essentially of a block copolymer.
18. (Withdrawn) A method of making the composition of claim 11.
19. (Withdrawn) A method of using a hot melt adhesive composition comprising:
 - (a) providing a hot melt adhesive composition comprising:
 - (i) an ethylene methyl methacrylate copolymer; and
 - (ii) a tackifying resin,

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with the proviso that the composition does not include a surfactant or a copolymer of ethylene and n-butyl acrylate; and
(b) applying the composition to a substrate.

20. (Withdrawn) The method of claim 19 wherein the method is a method of using the hot melt adhesive for book binding.